# **Chip Monolithic Ceramic Capacitors**



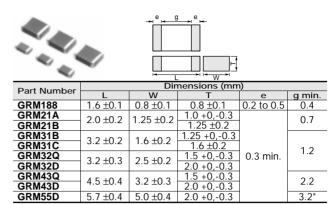
### Medium-voltage High-Capacitance for General-Use

#### ■ Features

- A new monolithic structure for small, high capacitance capable of operating at high voltage levels.
- 2. Sn-plated external electrodes realized good solderability.
- Use the GRM18/21/31 types with flow or reflow she soldering, and other types with reflow soldering only.

#### ■ Applications

- 1. Ideal for use as a hot-cold coupling for DC/DC converter.
- 2. Ideal for use on line filters and ringer detectors for telephones, facsimiles and modems.
- 3. Ideal for use on diode-snubber circuits for switching power supplies.



Part Number	Rated Voltage (V)	TC Code (Standard)	Capacitance	Length L (mm)	Width W (mm)	Thickness T (mm)	Electrode g min. (mm)	Electrode e (mm)
GRM188R72E221KW07D	DC250	X7R (EIA)	220pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E331KW07D	DC250	X7R (EIA)	330pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E471KW07D	DC250	X7R (EIA)	470pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E681KW07D	DC250	X7R (EIA)	680pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E102KW07D	DC250	X7R (EIA)	1000pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM21AR72E102KW01D	DC250	X7R (EIA)	1000pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM188R72E152KW07D	DC250	X7R (EIA)	1500pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM21AR72E152KW01D	DC250	X7R (EIA)	1500pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM188R72E222KW07D	DC250	X7R (EIA)	2200pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM21AR72E222KW01D	DC250	X7R (EIA)	2200pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21AR72E332KW01D	DC250	X7R (EIA)	3300pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21AR72E472KW01D	DC250	X7R (EIA)	4700pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21AR72E682KW01D	DC250	X7R (EIA)	6800pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21BR72E103KW03L	DC250	X7R (EIA)	10000pF ±10%	2.0	1.25	1.25	0.7	0.3 min.
GRM31BR72E153KW01L	DC250	X7R (EIA)	15000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72E223KW01L	DC250	X7R (EIA)	22000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31CR72E333KW03L	DC250	X7R (EIA)	33000pF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM31CR72E473KW03L	DC250	X7R (EIA)	47000pF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM32QR72E683KW01L	DC250	X7R (EIA)	68000pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM31CR72E104KW03L	DC250	X7R (EIA)	0.10μF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM32DR72E104KW01L	DC250	X7R (EIA)	0.10μF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43QR72E154KW01L	DC250	X7R (EIA)	0.15μF ±10%	4.5	3.2	1.5	2.2	0.3 min.
GRM32DR72E224KW01L	DC250	X7R (EIA)	0.22μF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43DR72E224KW01L	DC250	X7R (EIA)	0.22μF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM43DR72E334KW01L	DC250	X7R (EIA)	0.33μF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR72E334KW01L	DC250	X7R (EIA)	0.33μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM43DR72E474KW01L	DC250	X7R (EIA)	0.47μF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR72E474KW01L	DC250	X7R (EIA)	0.47μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM55DR72E105KW01L	DC250	X7R (EIA)	1.0μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM31BR72J102KW01L	DC630	X7R (EIA)	1000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J152KW01L	DC630	X7R (EIA)	1500pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J222KW01L	DC630	X7R (EIA)	2200pF ±10%	3.2	1.6	1.25	1.2	0.3 min.

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Part Number	Rated Voltage (V)	TC Code (Standard)	Capacitance	Length L (mm)	Width W (mm)	Thickness T (mm)	Electrode g min. (mm)	Electrode e (mm)
GRM31BR72J332KW01L	DC630	X7R (EIA)	3300pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J472KW01L	DC630	X7R (EIA)	4700pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J682KW01L	DC630	X7R (EIA)	6800pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J103KW01L	DC630	X7R (EIA)	10000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31CR72J153KW03L	DC630	X7R (EIA)	15000pF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM32QR72J223KW01L	DC630	X7R (EIA)	22000pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM32DR72J333KW01L	DC630	X7R (EIA)	33000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM32DR72J473KW01L	DC630	X7R (EIA)	47000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43QR72J683KW01L	DC630	X7R (EIA)	68000pF ±10%	4.5	3.2	1.5	2.2	0.3 min.
GRM43DR72J104KW01L	DC630	X7R (EIA)	0.10μF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR72J154KW01L	DC630	X7R (EIA)	0.15μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM55DR72J224KW01L	DC630	X7R (EIA)	0.22μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM31BR73A102KW01L	DC1000	X7R (EIA)	1000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A152KW01L	DC1000	X7R (EIA)	1500pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A222KW01L	DC1000	X7R (EIA)	2200pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A332KW01L	DC1000	X7R (EIA)	3300pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A472KW01L	DC1000	X7R (EIA)	4700pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM32QR73A682KW01L	DC1000	X7R (EIA)	6800pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM32QR73A103KW01L	DC1000	X7R (EIA)	10000pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM32DR73A153KW01L	DC1000	X7R (EIA)	15000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM32DR73A223KW01L	DC1000	X7R (EIA)	22000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43DR73A333KW01L	DC1000	X7R (EIA)	33000pF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM43DR73A473KW01L	DC1000	X7R (EIA)	47000pF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR73A104KW01L	DC1000	X7R (EIA)	0.10μF ±10%	5.7	5.0	2.0	2.5	0.3 min.

## **Specifications and Test Methods**

No.	Ite	m	Specifications	Test Method			
1	Operating Temperatu	re Range	-55 to +125℃	_			
2	Appearan	ce	No defects or abnormalities	Visual inspection			
3	Dimension	าร	Within the specified dimensions	Using calipers			
4	4 Dielectric Strength No defects or abnormalities			No failure should be observed when 150% of the rated voltage (200% of the rated voltage in case of rated voltage: DC250V, 120% of the rated voltage in case of rated voltage: DC1kV) is applied between the terminations for 1 to 5 sec., provided the charge/discharge current is less than 50mA.			
5 D <u>a</u>	Insulation R	esistance	C≥0.01μF : More than 100MΩ • μF C<0.01μF : More than 10,000MΩ	The insulation resistance should be measured with DC500±50V (DC250±50V in case of rated voltage : DC250V) and within 60±5 sec. of charging.			
6	Capacitar	ice	Within the specified tolerance	The capacitance/D.F. should be measured at 25°C at a frequency of 1±0.2kHz and a voltage of AC1±0.2V (r.m.s.)  • Pretreatment			
7	Dissipatio Factor (D.		0.025 max.	Perform a heat treatment at 150 <sup>+o</sup> <sub>10</sub> ℃ for 60±5 min. and then let sit for 24±2 hrs. at *room condition.			
8	Capacitan Temperati Character	ıre	Cap. Change Within ±15% (Temp. Range : −55 to +125°C)	The range of capacitance change compared with the 25°C value within −55 to +125°C should be within the specified range.  •Pretreatment  Perform a heat treatment at 150 <sup>+0</sup> / <sub>-10</sub> °C for 60±5 min. and then let sit for 24±2 hrs. at *room condition.			
9	Adhesive Strength of Termination		No removal of the terminations or other defect should occur.	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 1 using a eutectic solder.  Then apply 10N force in the direction of the arrow.  The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.  10N (5N: Size 1.6×0.8mm only), 10±1s Speed: 1.0mm/s  Glass Epoxy Board			
		_		Fig. 1			
		Appearance	No defects or abnormalities	Solder the capacitor to the test jig (glass epoxy board).  The capacitor should be subjected to a simple harmonic motion			
10	Vibration Resistance	D.F.	Within the specified tolerance  0.025 max.	having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2 hrs. in each 3 mutually perpendicular directions (total of 6 hrs.).  Solder resist  Glass Epoxy Board			
			No cracking or marking defects should occur.	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 2 using a eutectic solder.			
11	11 Deflection		Dimension (mm)	Then apply a force in the direction shown in Fig. 3.  The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.  Pressurizing speed: 1.0mm/s  Pressurize  Capacitance meter  (in mm)  Fig. 3			

<sup>\* &</sup>quot;Room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmospheric pressure : 86 to 106kPa

## **Specifications and Test Methods**

$\overline{A}$	Continued from the preceding page.							
No.	Ite	Item Specifications		Test Method				
12	Termination		75% of the terminations are to be soldered evenly and continuously.	Immerse the capacitor in a solution of ethanol (JIS-K-8101) rosin (JIS-K-5902) (25% rosin in weight proportion). Immerse in eutectic solder solution for 2±0.5 sec. at 235±5 Immersing speed: 25±2.5mm/s				
		Appearance	No marking defects		apacitor at 120 to 150°C* for 1 r			
13	Resistance to Soldering Heat	Capacitance Change	Within ±10%	10±1 sec. Let	capacitor in eutectic solder solu sit at *room condition for 24±2 peed: 25±2.5mm/s			
		D.F.	0.025 max.	Pretreatmen		2015		
		I.R.	$C \ge 0.01 \mu F$ : More than $100 M \Omega \cdot \mu F$ C<0.01 μF : More than $10,000 M \Omega$		eat treatment at $150_{-18}^{+18}$ °C for 6 $^{+2}$ hrs. at *room condition.	60±5 min. and then		
					or more than 3.2×2.5mm			
		Dielectric	In accordance with item No.4	Step 1	Temperature 100°C to 120°C	Time 1 min.		
		Strength		2	170°C to 200°C	1 min.		
		Appearance	No marking defects	Fix the capaci	tor to the supporting jig (glass	epoxy board) shown		
		Capacitance		in Fig. 4 using a eutectic solder.  Perform the 5 cycles according to the 4 heat treatments listed in the following table.				
		Change	Within ±7.5%					
		D.F.	0.025 max.	_	2 hrs. at *room condition, then	measure.		
			C≧0.01μF : More than 100MΩ • μF	Step	Temperature (°C)	Time (min.)		
		I.R.	C<0.01 $\mu$ F : More than 10,000M $\Omega$	1	Min. Operating Temp.±3	30±3		
				2	Room Temp.	2 to 3		
				34	Max. Operating Temp.±2  Room Temp.	30±3 2 to 3		
14	Temperature			-		2100		
	Cycle				•Pretreatment  Perform a heat treatment at 150 ± 100 ℃ for 60±5 min. and then			
				let sit for $24\pm2$ hrs. at *room condition.				
		Dielectric	In accordance with item No.4					
		Strength						
				Glass Epoxy Board  Fig. 4				
		Appearance	No marking defects		· · · · · · · · · · · · · · · · · · ·			
		Capacitance	Within ±15%		itor sit at 40±2°C and relative h	umidity of 90 to 95%		
		Change	Within ±13%	for 500 ± 20 hrs.  Remove and let sit for 24±2 hrs. at *room condition, then measure.				
15	Humidity (Steady	D.F.	0.05 max.					
	State)	I.R.	C≥0.01μF : More than 10MΩ • μF	•Pretreatmen		2015 : 14		
			C<0.01μF : More than 1,000MΩ		eat treatment at $150 \pm_{1} \% \%$ for $6 \pm_{1} \%$ for $6 \pm_{1} \%$	50±5 min. and then		
		Dielectric Strength	In accordance with item No.4	100 00 101 2 12				
		Appearance	No marking defects		f the rated voltage (150% of th			
		Capacitance	Within ±15% (rated voltage : DC250V, DC630V)		voltage: DC250V, 110% of the			
	Life -	Change	Within ±20% (rated voltage : DC1kV)		voltage : DC1kV) for 1,000±⁴8 perature ±3℃. Remove and le			
16		D.F.	0.05 max.	*room condition	on, then measure.			
		I.R.	C≥0.01μF : More than 10MΩ • μF C<0.01μF : More than 1,000MΩ	The charge/discharge current is less than 50mA.  •Pretreatment Apply test voltage for 60±5 min. at test temperature.				
		Dielectric						
		Strength	In accordance with item No.4	Remove and	Remove and let sit for 24±2 hrs. at *room condition.			
	Humidity	Appearance	No marking defects		Apply the rated voltage at 40±2°C and relative humidity of 90 to 95% for 500±2°d hrs.  Remove and let sit for 24±2 hrs. at *room condition, then			
		Capacitance	Within ±15%					
	Loading	Change						
17	(Application :	D.F.	0.05 max.	measure.				
	DC250V, DC630V	I.R.	C≥0.01μF : More than 10MΩ • μF C<0.01μF : More than 1,000MΩ		•Pretreatment Apply test voltage for 60±5 min. at test temperature.			
	item)	Dielectric Strength	In accordance with item No.4	Remove and let sit for 24±2 hrs. at *room condition.				
		Judigui						

<sup>\* &</sup>quot;Room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmospheric pressure : 86 to 106kPa